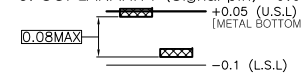


※ NOTE

- PLATING
 - CONTACT (JIG Plating)
 - Contact Area : Au 0.05 μ m Min. over Pd-Ni 0.75 μ m Min. over Ni 2.0~5.0 μ m.
 - Lead Area : Au 0.05 μ m Min. over Ni 0.2~3.0 μ m.
 - METAL SHELL (Dipping Plating) : Sn 1.0~3.0 μ m over Ni 0.2~3.0 μ m (Reflow Finish)
- ☆ : C.T.Q
- COPLANARITY (Signal pin) : 0.08 MAX



3	METAL SHELL	STS304	Note. 1	t0.3
2	CONTACT	Copper Alloy	Note. 1	t0.2
1	HOUSING	LCP	Blue Color	UL94V-0
No	Descriptions	Material	Finish	Remarks
General Tolerance		Scale	N/S	Units mm
Dimension		Date	2012. 09. 12	Sheet 1 of 1
X.X	± 0.2	Drawn	Design	Checked
X.XX	± 0.1	T. C. KIM		
X.XXX	± 0.05	Reviewed	Approved	
ANGLE	$\pm 1^\circ$	JNTC CO., LTD.		
TITLE		HI09-AG0505 USB 3.0 SOCKET		
Customer Drawing		Rev. 0		
SW No.		DWG No. HI09-AG0505-A1		